



LightningMaster
Corporation

GROUNDING PLATE COPPER LM-GP-1212



APPLICATION: For use to enhance ground grid systems per UL 96 and NFPA 780.

DESCRIPTION: 12" X 12" copper ground plate (0.032" thick high conductivity copper sheet with UL 96 listed bonding plate). Available in custom sizes.

Notes:

- Meeting NFPA 780 4.13.6.1 requirements- A ground plate electrode shall have a minimum thickness of 0.032" and a minimum surface area of 2 sq. ft.
- NFPA 780 4.13.6.2 - The ground plate electrode shall be buried no less than 18" below grade.

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2100-A Palmetto St., Clearwater, FL 33765
800-749-6800

lightningmaster.com